

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHUN-CHING WU	03/13/2014
HSIANG-HUI TSAI	03/13/2014
PO-JEN WANG	03/13/2014
HUNG-CHE LIAO	03/13/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
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State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14104987
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DATE SIGNED:	04/14/2014
Total Attachments: 2	
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NP-14226-US-B
TSMC-2-13-1214

Inventor(s)-to-Assignee

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) SEMICONDUCTOR DEVICE STRUCTURE AND METHOD FOR MANUFACTURING THE SAME

The PATENT RIGHTS referred to in this agreement are:

- (check one) a patent application for this invention, executed by the ASSIGNOR(S) concurrently with this assignment.
- U.S. patent application Serial No. 14/104,987, filed on December 12, 2013
- a U.S. patent application based on PCT International Application No. _____ filed on (date) _____ (U.S. patent application Serial No. _____, if known).
- U.S. patent No. _____, issued _____.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

- (check one) U.S. patent rights only.
- Worldwide patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. or foreign patent application for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
(Address) NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN 300, R.O.C.

The ASSIGNEE is:

- (check one) An individual.
- A Partnership.
- A Corporation of TAIWAN, R.O.C. (specify state or country)
- (other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, hereby assign(s) the following rights to the ASSIGNEE, its successors and assigns:

- the full and exclusive right to the invention;
- the entire right, title and interest in and to the PATENT RIGHTS;
- the right to sue and recover for any past infringement; and
- the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

